

PRODUCT NUMBER
10121033-X01-XXXLF

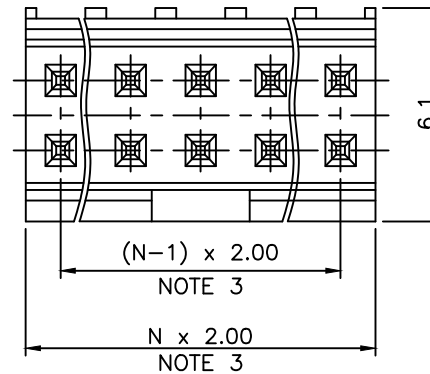
PLATING
S = 0.38µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
OVER 1.27µm MIN NICKEL
G = 0.76µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
OVER 1.27µm MIN NICKEL
F = GOLD FLASH ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
OVER 1.27µm MIN NICKEL

LEAD FREE
RoHS COMPATIBLE
SEE NOTE 6

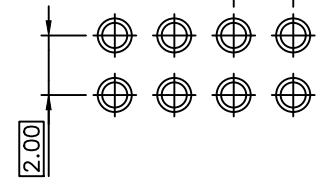
PACKAGING
SEE NOTE 5

TOTAL NUMBER OF
POSITIONS, 08 TO 34

VIEW WITHOUT PICK UP CAP



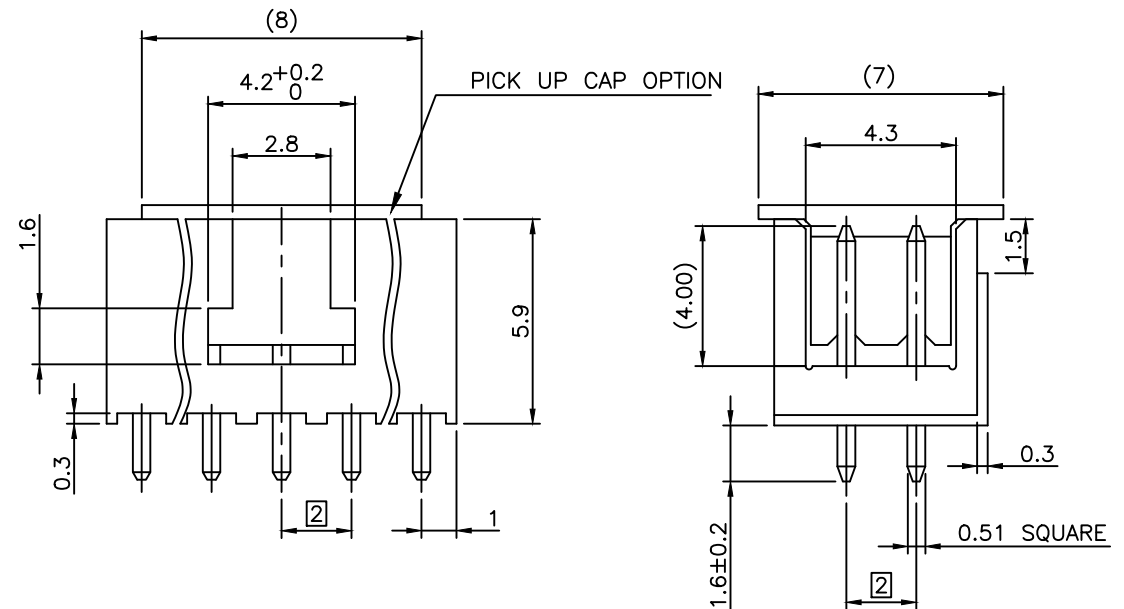
2.00 TYP
NON-ACCUMULATIVE



RECOMMENDED PCB LAYOUT
STENCIL DESIGN RECOMMENDATIONS
AS PER TA-896

NOTES:

- MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR CREAM
- MATERIAL TERMINAL: COPPER ALLOY
- TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
- 7N MIN. PIN RETENTION IN EITHER DIRECTION.
- PACKAGING:
A = TAPE & REEL WITH PICK UP CAP, AS AVAILABLE.
K = TAPE & REEL WITHOUT PICK UP CAP, AS AVAILABLE.
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - PLATING:
- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.
 - MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C PEAK TEMPERATURE FOR 30 SECONDS MAX
IN A CONVECTION, INFRA-RED, OR VAPOR PHASE
OR REFLOW OVEN
 - LABELLING:
- MEETS PACKAGING SPECS AS PER GS-14-920
 - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101				MINITEK	
ltr		ecn no		date		tolerances unless otherwise specified		title	
A		F12-0052		LMU 13.01.17		x.x ±0.30		SHR HEADER 2.00mm	
B		F-23051		AMA 16.01.15		x.xx ±0.13		2 WALLS VERT PIP	
C		F-39016		DDE 20.11.18		x.xxx ±0.05		scale 5:1	
D		F-281423		DDE 26.03.10		dr L.MULIN 12.05.10		dwg no sheet 1 of 1 size	
						enr J.COMPAGNON 12.05.10		10121033 A3	
						chr		type CUSTOMER Drawing	
						appd J.COMPAGNON 12.05.10			
sheet		revision							
index		sheet							